



Advance Product Change Notification

201405012A

Issue Date: 29-Jun-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to [view this notification online](#)



QUALITY

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323

Details of this Planned Change

Scheduled changes affect product types in SOT323 package only.

(1) The bond wire material will be changed from gold (Au) to copper (Cu). Implementation of change to copper wire as given by planned first shipment date below. Gold wire remains qualified for supply security reasons only.

(2) A second source mold compound supplier will be introduced for copper wire products.

Old product: wire material is Au (with currently used mold compound suppliers)

Changed product: wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers)

The design and materials of all other components will remain unchanged: die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature are being performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Plan this Change

(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

(2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM. The second source is already a well-established mold compound supplier for NXP GA discrete semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Samples can be ordered now and will be shipped latest after FPCN issue date.

Production

Planned first shipment 01-Nov-2014

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification Issue Date Effective Date Title

201309012F0107-May-2014	05-Aug-2014	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323
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Timing and Logistics

The Self Qualification Report will be ready on 11-Jul-2014.

The Final PCN is planned to be issued on: 28-Jul-2014.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 29-Jul-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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